IN THE CLAIMS:

Please amend the claims as follows:

- 1. (Canceled)
- 2. (Canceled)
- 3. (Previously Presented) A heat-resistant film comprising a film substrate and a heat-resistant slip layer disposed on one surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein the binder is polymethylmethacrylate.
- 4. (Canceled)
- 5. (Previously Presented) A heat-resistant film comprising a film substrate and a heat-resistant slip layer disposed on one surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

6. (Canceled)

7. (Previously Presented) The heat-resistant film according to claim 3, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

8. (Previously Presented) The heat-resistant film according to claim 3, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

9. (Previously Presented) The heat-resistant film according to claim 5, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

1

10-12. (Canceled)

13. (Previously Presented) The heat-resistant film according to claim 7, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

14-18. (Canceled)

19. (Previously Presented) A thermal transfer recording medium including a film substrate and a thermal transfer ink layer disposed on one surface of the film substrate and a heat-resistant slip layer disposed on the other surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein the binder is polymethylmethacrylate.

20. (Canceled)

- 21. (Previously Presented) A thermal transfer recording medium including a film substrate and a thermal transfer ink layer disposed on one surface of the film substrate and a heat-resistant slip layer disposed on the other surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.
- 22. (Previously Presented) The heat-resistant film according to claim 3, wherein the

free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.

- 23. (Previously Presented) The heat-resistant film according to claim 5, wherein the free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.
- 24. (Previously Presented) The heat-resistant film according to claim 22, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.
- 25. (Previously Presented) The heat-resistant film according to claim 22, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.
- 26. (Previously Presented) The heat-resistant film according to claim 23, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.